

FEBRUARY 1975

DIGITAL 8000 SERIES TTL/MEMORY

### DESCRIPTION

The 82S116 and 82S117 are Schottky clamped TTL, read/write memory arrays organized as 256 words of one bit each. They feature either open collector or tri-state output options for optimization of word expansion in bussed organizations. Memory expansion is further enhanced by full on-chip address decoding, 3 chip enable inputs and PNP input transistors which reduce input loading to  $25\mu\text{A}$  for a "1" level, and  $-100\mu\text{A}$  for a "0" level.

During WRITE operation, the logical state of the output of both devices follows the complement of the data input being written. This feature allows faster execution of WRITE-READ cycles, enhancing the performance of systems utilizing indirect addressing modes, and/or requiring immediate verification following a WRITE cycle.

Both devices have fast read access and write cycle times, and thus are ideally suited in high-speed memory applications such as "Cache", buffers, scratch pads, writable control stores, etc.

Both 82S116 and 82S117 devices are available in the commercial temperature range. For the commercial temperature range, ( $0^\circ\text{C}$  to  $+75^\circ\text{C}$ ) specify N82S116/117, B or F.

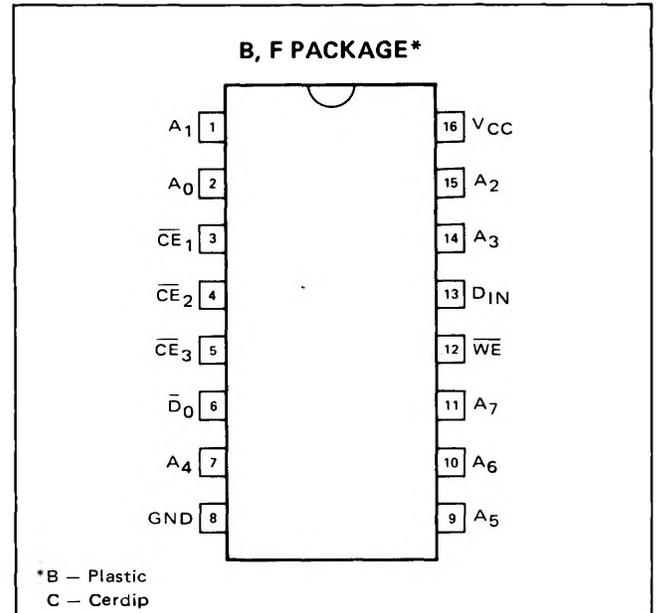
### FEATURES

- ORGANIZATION – 256 X 1
- ADDRESS ACCESS TIME – 40ns, MAXIMUM
- WRITE CYCLE TIME – 25ns, MAXIMUM
- POWER DISSIPATION – 1.5mW/BIT TYPICAL
- INPUT LOADING – ( $-100\mu\text{A}$ ) MAXIMUM
- OUTPUT FOLLOWS COMPLEMENT OF DATA INPUT DURING WRITE
- ON-CHIP ADDRESS DECODING
- OUTPUT OPTION:  
TRI-STATE – 82S116  
OPEN COLLECTOR – 82S117
- 16 PIN CERAMIC DIP

### APPLICATIONS

BUFFER MEMORY  
WRITABLE CONTROL STORE  
MEMORY MAPPING  
PUSH DOWN STACK  
SCRATCH PAD

### PIN CONFIGURATION



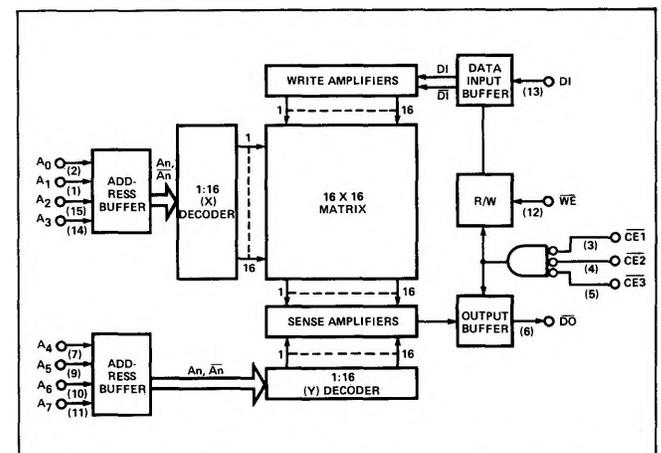
### TRUTH TABLE

MODE	$\overline{\text{CE}}^*$	$\overline{\text{WE}}$	$\text{D}_{\text{IN}}$	$\overline{\text{D}}_{\text{OUT}}$	
				82S116	82S117
READ	0	1	X	STORED DATA	STORED DATA
WRITE "0"	0	0	0	1	1
WRITE "1"	0	0	1	0	0
DISABLED	1	X	X	High-Z	1

\*"0" = All  $\overline{\text{CE}}$  inputs low; "1" = one or more  $\overline{\text{CE}}$  inputs high.

X = Don't care.

### BLOCK DIAGRAM



## ABSOLUTE MAXIMUM RATINGS

PARAMETER	RATING	UNIT
$V_{CC}$ Power Supply Voltage	+7	Vdc
$V_{IN}$ Input Voltage	+5.5	Vdc
$V_{OUT}$ High Level Output Voltage (82S117)	+5.5	Vdc
$V_O$ Off-State Output Voltage (82S116)	+5.5	Vdc
$T_A$ Operating Temperature Range	0° to +75°	°C
$T_{stg}$ Storage Temperature Range	-65° to +150°	°C

ELECTRICAL CHARACTERISTICS  $0^{\circ}\text{C} \leq T_A \leq 75^{\circ}\text{C}$ ,  $4.75\text{V} \leq V_{CC} \leq 5.25\text{V}$ 

PARAMETER	TEST CONDITIONS	LIMITS			UNIT	NOTES
		MIN	TYP <sup>2</sup>	MAX		
$V_{IH}$ High-Level Input Voltage	$V_{CC} = 5.25\text{V}$	2.0			V	
$V_{IL}$ Low-Level Input Voltage	$V_{CC} = 4.75\text{V}$			0.85	V	1
$V_{IC}$ Input Clamp Voltage	$V_{CC} = 4.75\text{V}$ , $I_{IN} = -12\text{ mA}$		-1.0	-1.5	V	1,8
$V_{OH}$ High-Level Output Voltage (82S116)	$V_{CC} = 4.75\text{V}$ , $I_{OH} = -3.2\text{ mA}$	2.6			V	1,6
$V_{OL}$ Low-Level Output Voltage	$V_{CC} = 4.75\text{V}$ , $I_{OL} = 16\text{ mA}$		0.35	0.45	V	1,7
$I_{OLK}$ Output Leakage Current (82S117)	$V_{OUT} = 5.5\text{V}$		1	40	$\mu\text{A}$	5
$I_{O(OFF)}$ HI-Z State Output Current (82S116)	$V_{OUT} = 5.5\text{V}$		1	40	$\mu\text{A}$	5
	$V_{OUT} = 0.45\text{V}$		-1	-40	$\mu\text{A}$	5
$I_{IH}$ High-Level Input Current	$V_{CC} = 5.25\text{V}$ , $V_{IN} = 5.5\text{V}$		1	25	$\mu\text{A}$	8
$I_{IL}$ Low-Level Input Current	$V_{CC} = 5.25\text{V}$ , $V_{IN} = 0.45\text{V}$		-10	-100	$\mu\text{A}$	8
$I_{OS}$ Short-Circuit Output Current (82S116)	$V_{CC} = 5.25\text{V}$ , $V_O = 0\text{V}$	-20		-70	mA	3
$I_{CC}$ $V_{CC}$ Supply Current (82S116) $V_{CC}$ Supply Current (82S117)	$V_{CC} = 5.25\text{V}$		80	115	mA	4
	$V_{CC} = 5.25\text{V}$		80	115	mA	4
$C_{IN}$ Input Capacitance	$V_{IN} = 2.0\text{V}$	$V_{CC} = 5.0\text{V}$		5	pF	
$C_{OUT}$ Output Capacitance	$V_{OUT} = 2.0\text{V}$			8		

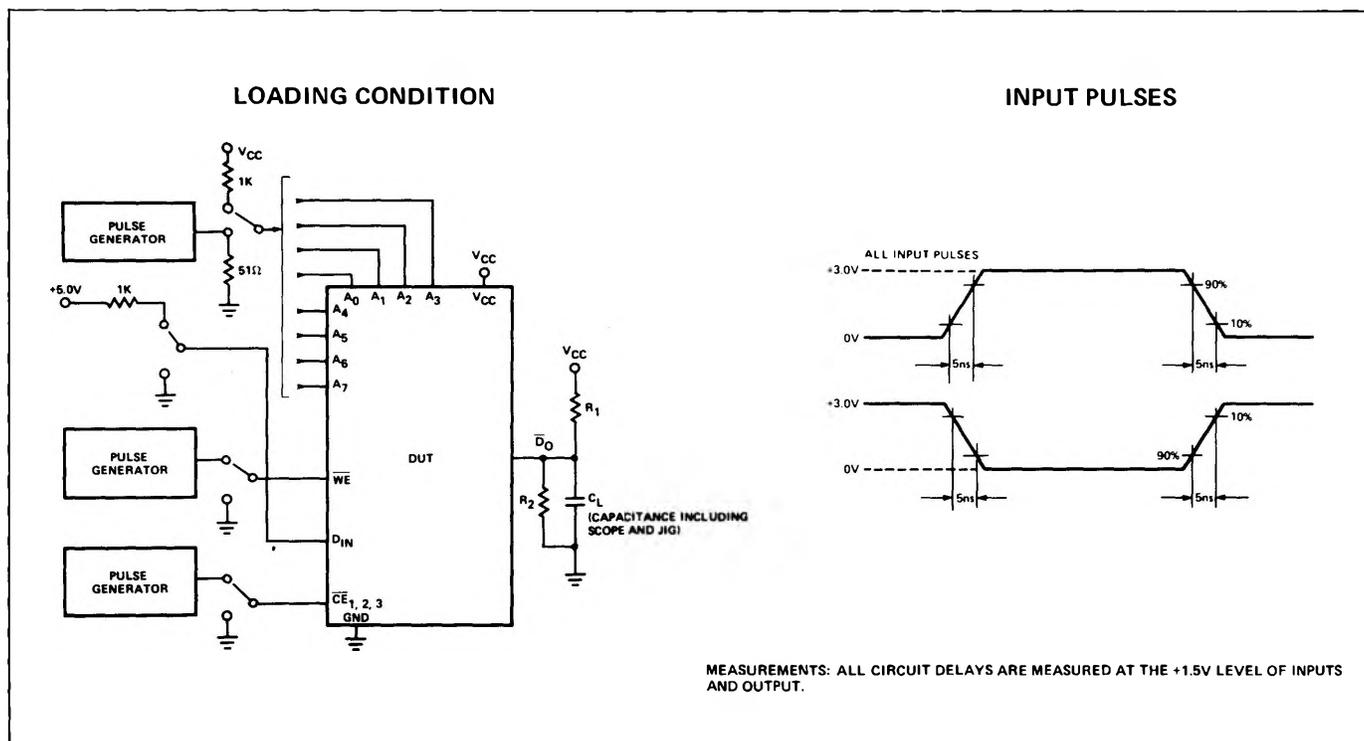
## NOTES:

- All voltage values are with respect to network ground terminal.
- All typical values are at  $V_{CC} = 5\text{V}$ ,  $T_A = +25^{\circ}\text{C}$ .
- Duration of the short-circuit should not exceed one second.
- $I_{CC}$  is measured with the write enable and memory enable inputs grounded, all other inputs at 4.5V, and the output open.
- Measured with  $V_{IH}$  applied to  $\overline{CE1}$ ,  $\overline{CE2}$  and  $\overline{CE3}$ .
- Measured with a logic "0" stored and  $V_{IL}$  applied to  $\overline{CE1}$ ,  $\overline{CE2}$  and  $\overline{CE3}$ .
- Measured with a logic "1" stored. Output sink current is supplied through a resistor to  $V_{CC}$ .
- Test each input one at the time.

SWITCHING CHARACTERISTICS  $0^{\circ}\text{C} \leq T_A \leq +75^{\circ}\text{C}$ ,  $4.75\text{V} \leq V_{CC} \leq 5.25\text{V}$

PARAMETER	TEST CONDITIONS	LIMITS			UNIT	NOTE
		MIN	TYP <sup>1</sup>	MAX		
<b>Propagation Delays</b>						
$T_{AA}$ Address Access Time			30	40	ns	
$T_{CE}$ Chip Enable Access Time	$R_1 = 270\Omega$		15	25	ns	
$T_{CD}$ Chip Enable Output Disable Time	$R_2 = 600\Omega$		15	25	ns	
$T_{WD}$ Write Enable to Output Disable Time	$C_L = 30\text{pF}$		30	40	ns	
<b>Write Set-up Times</b>						
$T_{WSA}$ Address to Write Enable		0	-5		ns	
$T_{WSD}$ Data In to Write Enable		25	15		ns	
$T_{WSC}$ $\overline{CE}$ to Write Enable		0	-5		ns	
<b>Write Hold Times</b>						
$T_{WHA}$ Address to Write Enable		0	-5		ns	
$T_{WHD}$ Data In to Write Enable		0	-5		ns	
$T_{WHC}$ $\overline{CE}$ to Write Enable		0	-5		ns	
$T_{Wp}$ Write Enable Pulse Width		25	15		ns	2

AC TEST LOAD

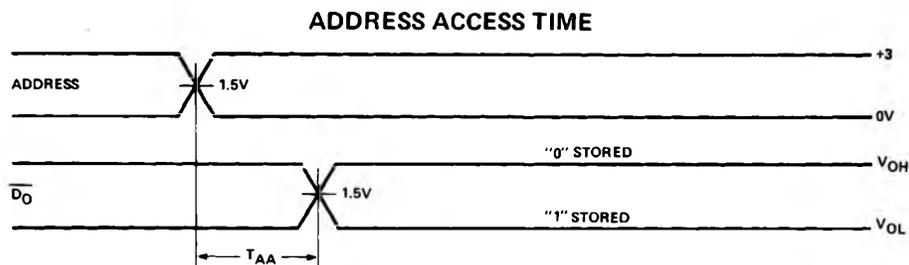


NOTES:

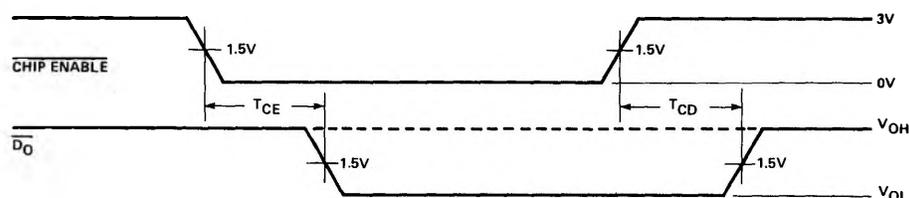
1. Typical values are at  $V_{CC} = +5.0\text{V}$ , and  $T_A = +25^{\circ}\text{C}$ .
2. Minimum required to guarantee a WRITE into the slowest bit.

SWITCHING PARAMETERS MEASUREMENT INFORMATION

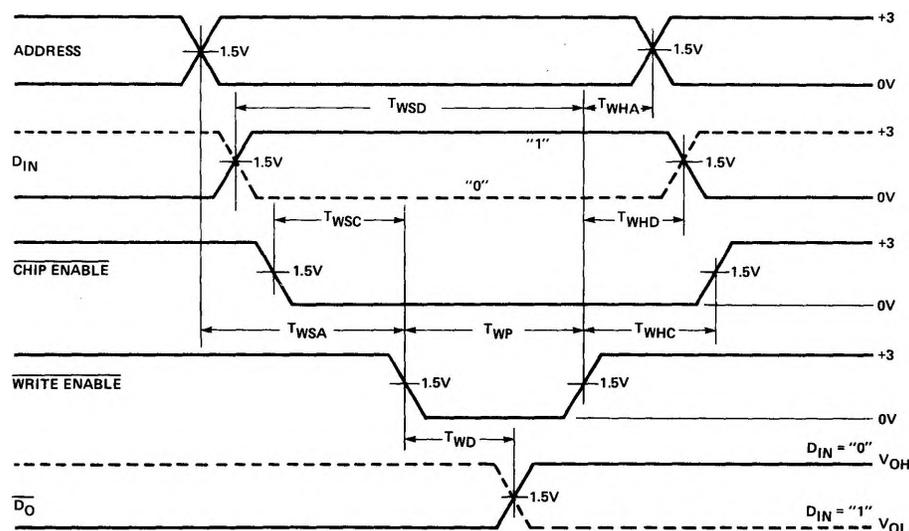
READ CYCLE



CHIP ENABLE/DISABLE TIMES



WRITE CYCLE



MEMORY TIMING DEFINITIONS

$T_{CE}$	Delay between beginning of CHIP ENABLE low (with ADDRESS valid) and when DATA OUTPUT becomes valid.	$T_{WP}$	Width of WRITE ENABLE pulse.
$T_{CD}$	Delay between when CHIP ENABLE becomes high and DATA OUTPUT is in off state.	$T_{WSA}$	Required delay between beginning of valid ADDRESS and beginning of WRITE ENABLE pulse.
$T_{AA}$	Delay between beginning of valid ADDRESS (with CHIP ENABLE low) and when DATA OUTPUT becomes valid.	$T_{WSD}$	Required delay between beginning of valid DATA INPUT and end of WRITE ENABLE pulse.
$T_{WSC}$	Required delay between beginning of valid CHIP ENABLE and beginning of WRITE ENABLE pulse.	$T_{WD}$	Delay between beginning of WRITE ENABLE pulse and when DATA OUTPUT reflects complement of DATA INPUT.
$T_{WHD}$	Required delay between end of WRITE ENABLE pulse and end of valid INPUT DATA.	$T_{WHC}$	Required delay between end of WRITE ENABLE pulse and end of CHIP ENABLE.
		$T_{WHA}$	Required delay between end of WRITE ENABLE pulse and end of valid ADDRESS.